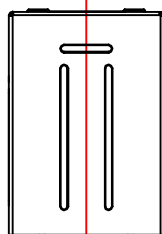
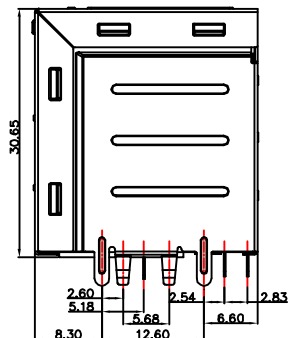


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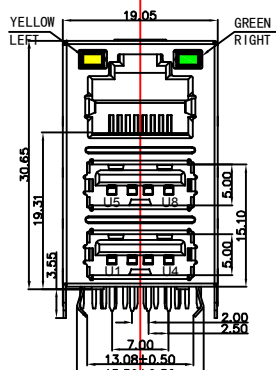
REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2017.9.14



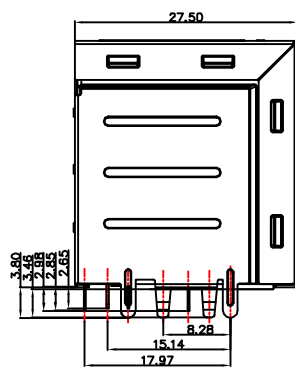
TOP VIEW



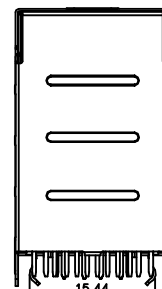
LEFT SIDE VIEW



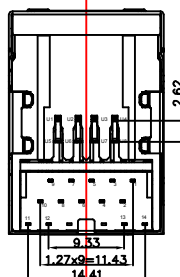
FRONT VIEW



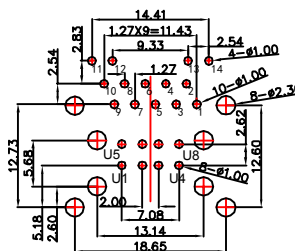
RIGHT SIDE VIEW



BACK VIEW



BOTTOM VIEW



RECOMMENDED PCB LAYOUT
VIEWED FROM COMPONENT SIDE

MATERIAL:

HOUSING: PBT,UL94V-0,BLACK.
TERMINALS BRACKET: PBT,UL94V-0,BLACK.
SHIELD: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.
TERMINAL: PHOSPHOR BRONZE C5210,T=0.35MM,
6U" GOLD PLATING ON CONTACT AREA.

MECHANICAL:

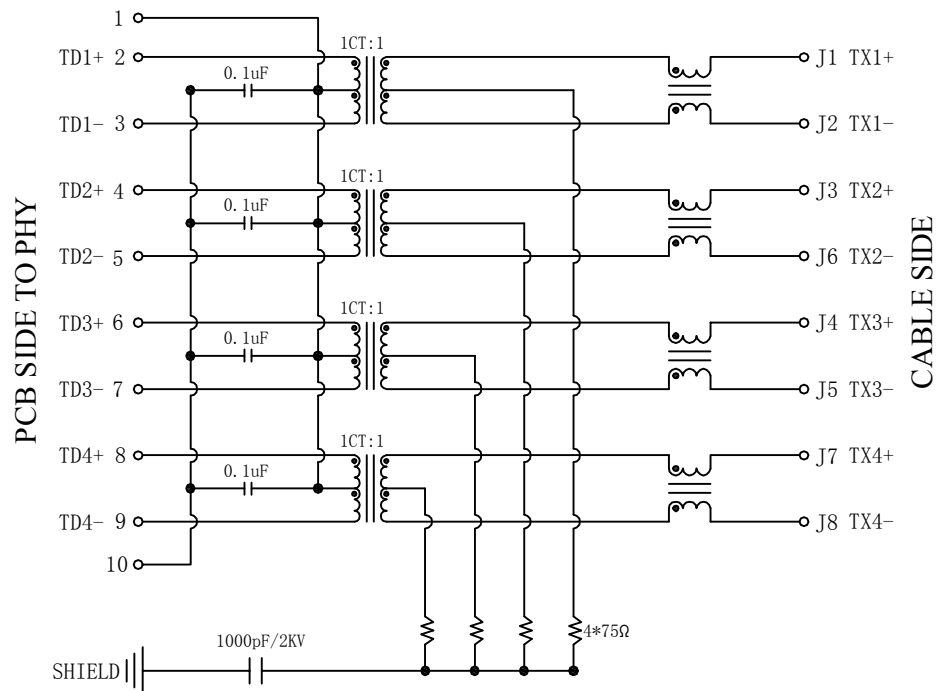
DURABILITY: 750 CYCLES MIN.
MATING FORCE: 30N MAX.
OPERATING TEMPERATURE: -40°C~+85°C.
STORAGE TEMPERATURE: -40°C~+85°C.
ALL CRITICAL DIMENSIONS WITH "*"

XYFWCN

TITLE: RJ45+双USB2.0 1000BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: RJ-711Q019AB1WD080	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 1/3		.x±0.30	.x°±2.0°	DESIGND BY: MQ.Qu
			.xx±0.25	.xx°±1.5°	
			.xxx±0.10	.xxx°±1.0°	

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REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2017.9.14

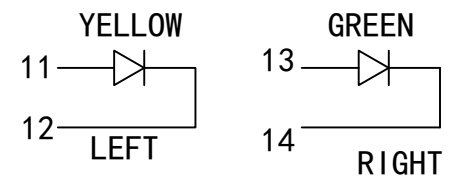


Electrical:

- Turn ratio: 2~3: J1~J2=1CT:1CT(±2%).
4~5: J3~J6=1CT:1CT(±2%).
6~7: J4~J5=1CT:1CT(±2%).
8~9: J7~J8=1CT:1CT(±2%).
- OCL: 350uH Min. at 100KHz 100mV 8mA DC.
- Insertion Loss: -1.0 dB Max 1~100MHz.
- Return loss: -20dB Min 1~10MHz;
-1 6dB Min 10~30MHz;
-1 2dB Min 30~60MHz;
-10dB Min 60~80MHz.
- Cross talk: -40dB Min 1~30MHz;
-35dB Min 30~60MHz;
-30dB Min 60~100MHz;
- CMR: -35dB Min 1~100MHz;
- Hi-Pot: 1500V AC & 2250V DC
6S 1mA PRI TO SEC

LED Specification

Standard LED Color	LED Wavelength	Foward(A)	Foward(V)
Green	568nm	20mA	1.8-2.8V
Yellow	585nm	20mA	1.8-2.8V



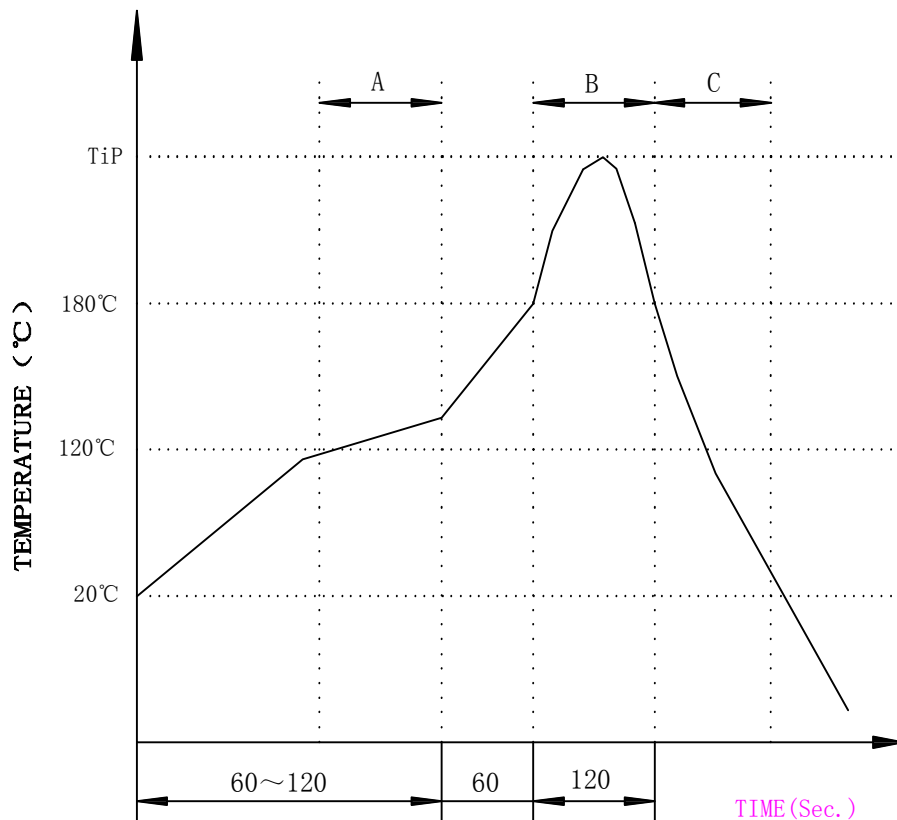
XYFWCN

TITLE: RJ45+双USB2.0 1000BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: RJ-711Q019AB1WD080	SACLE 1:1	REV A0	x±0.35 .x±0.30	x°±3.0° .x°±2.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 2/3		.xx±0.25 .xxx±0.10	.xx°±1.5° .xxx°±1.0°	DESIGND BY: MQ.Qu

REACH & RoHS
COMPLIANT

PROFILE OF WAVE SOLDER

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2017.9.14



A.Preheating B.Soldering C.Gradual Cooling
 Tip temperature:260±5°C.
 Tip temperature time:5Sec Max.
 Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

Remarks: after wave soldering, the plastic
 positioning columns of the product which under the
 PCB will be slightly melted, but it won't affect its
 function.

XYFWCN

TITLE: RJ45+双USB2.0 1000BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: RJ-711Q019AB1WD080	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 3/3		.xx±0.25	.xx°±1.5°	DESIGND BY: MQ.Qu
			.xxx±0.10	.xxx°±1.0°	